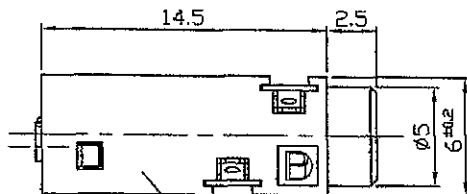
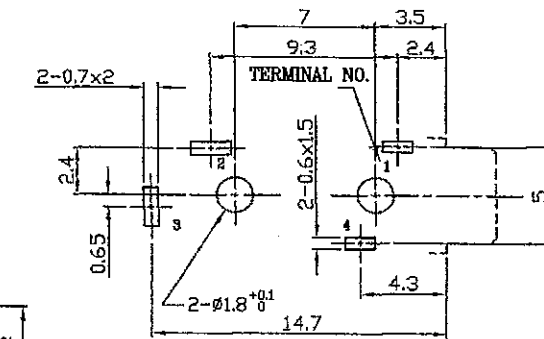
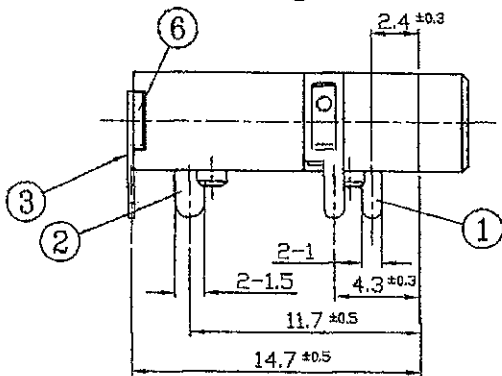


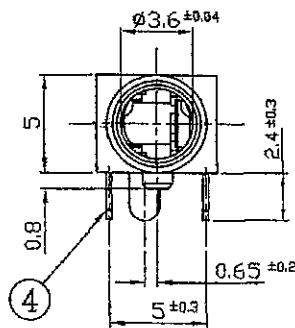
3D VIEW SCALE 2/1



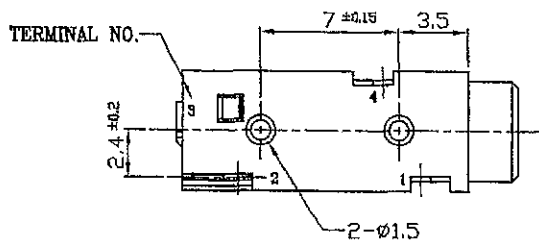
5



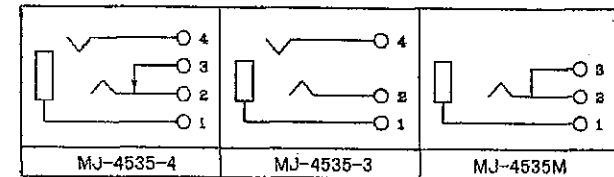
PC BOARD HOLE LAYOUT (Tols:±0.1)  
(VIEW FROM DIRECTION OF INSERTION TO PCB)



4



REVISION			
LTR	DESCRIPTION	DATE	APPROVED
VER.1	Replace old version issued on 07-07-2001	03-03-2011	K.F.M



CIRCUIT DIAGRAM

6	BACK COVER	1	PA66/GF RESIN	BLACK
5	JACK CASING	1	PA66/GF RESIN	SEE TABLE 1
4	RING SPRING	1	PBs	0.2t Ag-PLATED
3	SHUNT TERMINAL	1	BRASS	0.3t Ag-PLATED
2	TIP SPRING	1	COPPER ALLOY	0.25t Ag-PLATED
1	EARTH TERMINAL	1	PBs	0.2t Ag-PLATED
NO.	PART NAME	QTY	MAT'L	RMK

TOLERANCES X ≤ 5 = ±0.10 X > 5 = ±0.30 ANGULAR = ± --- DO NOT SCALE DWG.	PART NAME		SCALE
	ø3.5 STEREO EARPHONE JACK		
	MATL		DATE
	AS SHOWN IN TABLE		
DATE		DRN / APPD.	
03-03-2011			Y.H.TSANG/K.F.M

SHOGYO INTERNATIONAL CORP.  
#MJ-4535 SERIES